



Overmold Assembly Build Sheet

Original request
 Changed request Rev # _____

QP Internal S.O. #: _____

QP Quote #: _____

QP Sales Contact: _____

CUSTOMER CONTACT INFORMATION

Company: _____ Contact Name: _____ Date: _____

Phone: _____ Email: _____

P.O. #: _____

Is this item under the jurisdiction of the International Traffic in Arms Regulations (ITAR)? Yes No

DELIVERY REQUEST

LEAD TIMES WILL VARY BASED ON SCOPE OF WORK AND QUANTITY.

STANDARD LEAD TIME FOR BENCHMARK ORDER (PKG: QFN, PKG QTY: <200, WIRE COUNT: <50, SINGLE DIE ATTACH) IS 5 DAYS. EXPEDITE (4 DAYS). PREMIUM (3 DAYS).

Standard Expedite Premium

DIE INFORMATION:

ALL WAFER PROCESSING REQUIRES A BACKGRIND/DICING BUILD SHEET TO BE COMPLETED AND ATTACHED SEPARATELY.

Die Format: Waffle Pack Gel-Pak Diced Wafer on Tape Wafer (requires processing) Other: _____

Die Size: _____ X _____ μ m or mils (a) Wafer ID/Die ID: (b) Lot # (c) Qty of Devices to be Assembled from ID

Pad Pitch: _____ X _____ μ m or mils Bond 1a. _____ 1b. _____ 1c. _____

Pad Dims: _____ X _____ μ m or mils Bond 2a. _____ 2b. _____ 2c. _____

Pad Opening: _____ X _____ μ m or mils 3a. _____ 3b. _____ 3c. _____

Thickness: _____ μ m or mils 4a. _____ 4b. _____ 4c. _____

Metalization: Aluminum Gold Other (Specify): _____ Probed? Yes No Passivated? Yes No

DEVICE INFORMATION

Device Name: _____ Pin Count: _____ Lead Pitch: _____ Die Per Package: _____ Wire Count Per Package: _____

Qty of Devices to be Assembled: _____ Body Size (mm): _____ X _____

Packages provided by: Customer Quik-Pak

Package Type: QFN QP Package Part #: _____

Package Description: _____

Package Thickness (mm) .45 .70 .90 1.37 1.45 2.00

SPECIAL INSTRUCTIONS (Attach additional documents if needed)

CUSTOMER FURNISHED MATERIALS:

PLEASE LIST ANY ADDITIONAL CFMs THAT WILL BE SHIPPED TO QUIK-PAK. IF MORE SPACE IS NEEDED, PLEASE ATTACH ADDITIONAL DOCUMENTS.

1. _____ 2. _____ 3. _____

4. _____ 5. _____ 6. _____

7. _____ 8. _____ 9. _____

ASSEMBLY FLOW

ALL WIRE BONDING REQUIRES A BONDING DIAGRAM BE ATTACHED WITH CLEARLY LABELED PIN 1, DIE ORIENTATION, AND WIRE BONDS.

Please indicate file format: CAD Drawing Other (.jpg, .pdf, Powerpoint) etc.

SelectDieFrom: Center of Wafer(s) Wafer Map(s)

Die Attach Material (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT MATERIALS):

____ Conductive Epoxy ____ Thermally Conductive/Electrically Non-Conductive
____ Non-Conductive Epoxy ____ High Thermally Conductive/Electrically Conductive

Gold Wire Diameter (ENTER QTY IF SEPARATE LOTS REQUIRE DIFFERENT WIRE DIAMETER):

*STANDARD MATERIAL, OTHER OPTIONS MAY INCREASE COST/LEADTIME

____ 0.7 mil ____ 0.8 mil ____ 1.0 mil ____ 1.2 mil
____ 1.3 mil ____ 1.5 mil ____ 2.0 mil ____ Other (Al and Cu available - call for wire size)

Heavy Wire: ____ 5 mil ____ 10 mil ____ 15 mil ____ 20 mil

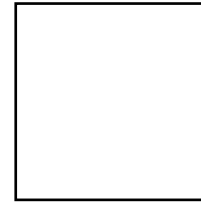
Gold Ribbon: ____ 1 X 2 ____ 1 X 3 ____ 1 X 4

Marking (MAX CHARACTER LENGTH AND NUMBER OF ROWS WILL VARY BASED ON PACKAGE SIZE. CONTACT QP FOR DESIGN APPROVAL AND COST):

Mark pin 1 on device?

No Custom Marking
Pad Print (White on Black) - Email artwork in native .EPS or .AI file format
Laser Mark (Black on Black) - Email artwork in native .EPS or .AI file format
Hand Mark (Max 1-3 characters):

Serialization (MAY INCREASE MARKING COSTS/LEADTIME). Please describe:



Mark pin 1 corner
and indicate how
marking should
appear on package
relative to pin 1.

SHIPPING (Contact QP with any special requests)

Reject Parts Disposition: Return to Customer Bag and Tag Destroy

*Unless otherwise noted all extra materials will be returned.

Shipping Method (Please Select)

Account #: _____

Pickup FedEx DHL UPS Courier Special Instructions

Ship To Address (Finished Product):

Attn: _____

Address: _____

Ship To Address (Excess Die and Materials):

Attn: _____

Address: _____

Include Certificate of Conformance

Ship Materials In

Trays

Tubes

Other: _____

Containers Provided by:

Quik-Pak

Customer

For Quik-Pak Internal Use Only:

Orders meeting one of the following requirements require signatures by representatives in the following departments:

☐ Over \$20k production ☐ ISO-13485 Processing ☐ Change in instructions after order has been released to

Sales: _____ Date: _____

Engineering: _____ Date: _____

Manufacturing: _____ Date: _____

QA: _____ Date: _____

Per Quik-Pak quality program, risk assessment is required on orders over \$100k and/or Medical orders built under ISO-13485 std.